



2878

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: V. Vaganov

Group Art Unit: 2878

Serial No.: 09/596,837

Examiner: G. Goudreau

Filed: 06/19/2000

Attorney's Docket

No.: SS-714-01

For:

METHOD FOR FABRICATING MICROSTRUCTURES WITH
DEEP ANISOTROPIC ETCHING OF THICK SILICON WAFERS

COMMISSIONER OF PATENTS
& TRADEMARKS
Washington, D.C. 20231

Date of this Paper:

December 12, 2002

RESPONSE TO RESTRICTION REQUIREMENT

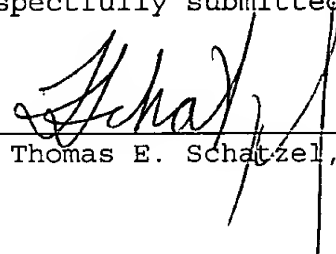
In response to the Patent Office Action mailed 11/18/2002, kindly enter the following:

Applicant respectfully traverses the merits of the request. However, applicant elects the isotropic dry etching step claims as indicated in the Office Action (i.e. claims 26, 29-30, 33-34, 48, 51-52, 55, 85, 88, 105, 108 and 115) in the event that no generic claims are finally found allowable.

Respectfully submitted,

Dated: 12/12/2002

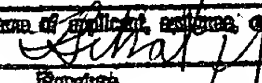
By


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I hereby certify that this correspondence is being deposited with the United States Postal Service in first class mail in an envelope addressed to Commissioner of Patents and Trademarks, Washington, D.C. 20231, on 12/12/2002

THOMAS E. SCHATZEL

 12/12/2002
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